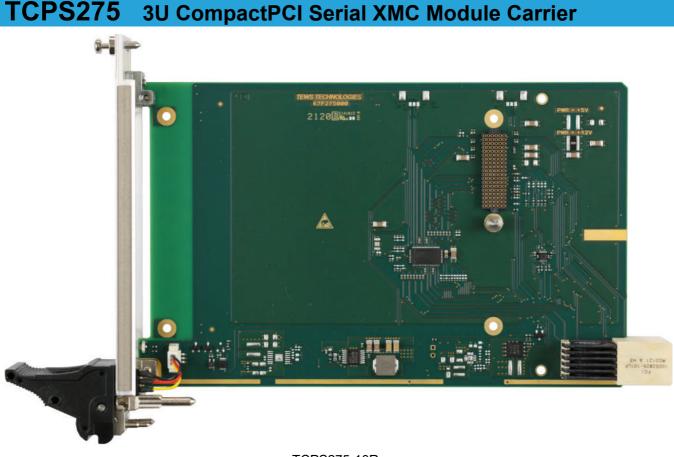


The Embedded I/O Company



TCPS275-10R

Application Information

The TCPS275 is a PICMG CPCI-S.0 R2.0 compatible 3U module that provides one slot for a single-width XMC module used to build modular, flexible and cost effective I/O solutions for all kinds of applications like process control, medical systems, telecommunication and traffic control.

The TCPS275 is a versatile solution to upgrade well known XMC I/O solutions to the CompactPCI Serial standard.

Technical Information

- Form Factor: 3U CPCI-S.0 R2.0
 Board size: 160 mm x 100 mm
- O One XMC site conforming to VITA 42.3
 - O PCIe Interface: x4, Rev. 3.0
 - O 12 V VPWR
 - XMC Front Panel I/O

The PCI Express x4 link from the host board to the XMC module is enhanced by a PCIe Gen3 Redriver, allowing safe operation of XMC modules in distributed PCIe systems.

The TCPS275 supports XMC front panel I/O. VPWR is 12 V for all variants.

Operating temperature -40°C to +85°C

 MTBF (MIL-HDBK217F/FN2 GB 20°C) TCPS275-10R: 1026000 h

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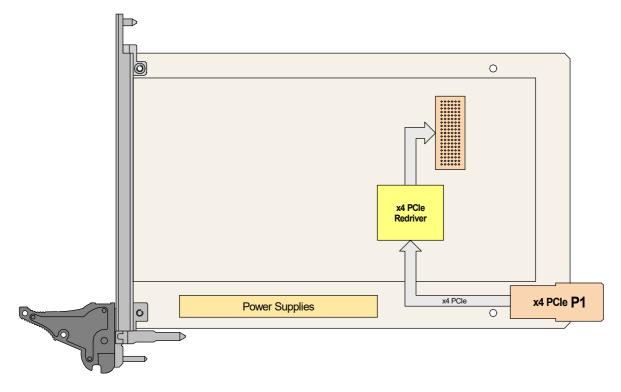
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TCPS275-10R

Order Information RoHS Compliant

TCPS275-10R 1 Slot Standard-XMC Carrier, PCIe x4, VPWR = 12V

For the availability of TCPS275 variants with VITA61.0 connectors please contact TEWS.

Documentation

TCPS275-DOC User Manual

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